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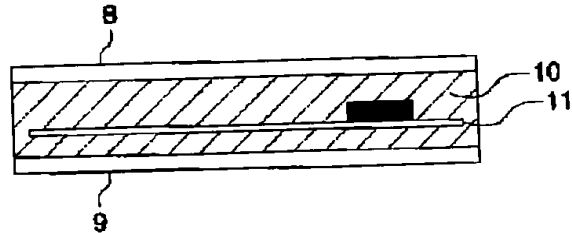
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TITLE : IC CARD



ABSTRACT : **PROBLEM TO BE SOLVED:** To make an IC card excellent in the smoothness of its surface by overlapping opposed first and second sheet materials with an adhesive agent layer using a hot-melt adhesive agent and sealing an IC module inside the adhesive agent layer.

SOLUTION: The hot-melt adhesive agent such as ethylene-vinylacetate copolymer system, a polyester system, a polyamide system, a thermoplastic elastomer system or a polyolefine system is applied on the first sheet material 8 having an image receiving layer on one surface and the second sheet material 9 by an applicator so as to obtain a prescribed thickness and, then, the adhesive agent layer 10 is formed. Then, the IC module 11 is mounted between the first and the second sheet materials 8 and 9 where the adhesive agent layer 10 is formed between them vertically. After that, an object where the IC module 11 is mounted between the first and the second sheet materials 8 and 9 is pressed for a prescribed time by a press which is heated to the adhesion temp. of the adhesive agent layer 10. Card-shaped blanking is executed so as to make a card.

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